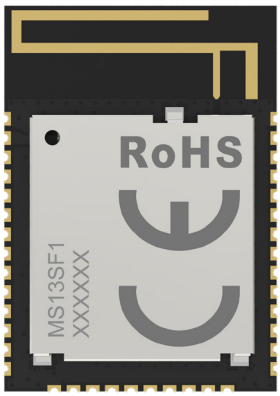
MINEWSEMI

Wi-Fi Command Module

MS13SF1



Datasheet

V 1.0.0

MS13SF1-ESP32

High-performance, multi-functional, cost-effective, passthrough support, WiFi 4 + BLE 4.2 combo module with full development resource support

The MS13SF1 is a versatile, high-performance and cost-effective wireless WiFi 4+ BLE4.2 combo module based on the ESP32-D0WD-V3 SoC. Xtensa® 32-bit LX6 with dual cores running at 240 MHz, 448 KB+8MB FLASH, 520KB+16KB RAM, integrated 2.4 GH transceiver, LNA and other powerful resources provide the perfect solution for 2.4G WiFi/BLE connectivity. The actual test distance under high interference conditions can reach 80M.

FEATURES

- 2.4G WiFi4 (802.11b/g/n) + BT/BLE 4.2
- High performance, dual-core SoC
- Supports AP, STA, AP+STA modes
- Supports AT, ESP-IDF development
- Compatible with ISO 11898-1, i.e., CAN specification 2.0
- Support SDIO, SPI, UART and other interfaces
- Supports OTA encryption upgrades

KEY PARAMETER

MS13SF1			
Chip Model	ESP32-D0WD	**Antenna**	PCB
Module size	25.5x18x2.2mm	**GPIO**	21
Flash	8MB+448KB	**RAM**	520KB+16KB
Receiving Sensitivity	BLE:-94dBm WiFi:-98dBm	**Transmission Power**	BLE:-12 ~ +9dBm WiFi:-12~ +20.5dBm
Current(TX)	19.5dBm- 239mA	**Current(RX)**	118mA

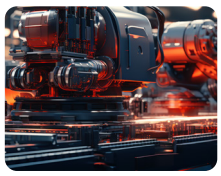
APPLICATION

Smart Healthcare

Consumer Electronics

Smart Agriculture

Security Equipment



Industrial Automation

Automotive Devices

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2 RELATED DOCUMENTS

- esp32-c6_Chip_Datasheet
  https://en.minewsemi.com/file/esp32-c6_Chip_Datasheet_EN.pdf
- MinewSemi_Product_Naming_Reference_Manual_V1.0
  https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf
- MinewSemi_Connectivity_Module_Catalogue_V2.0
  https://en.minewsemi.com/file/MinewSemi_Connectivity_Module_Catalogue_EN.pdf

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